

SOT1187-1

Plastic extremely thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON8
Package type industry code	XSON8
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	- - -
JEDEC package outline code	MO-229
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	7-10-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

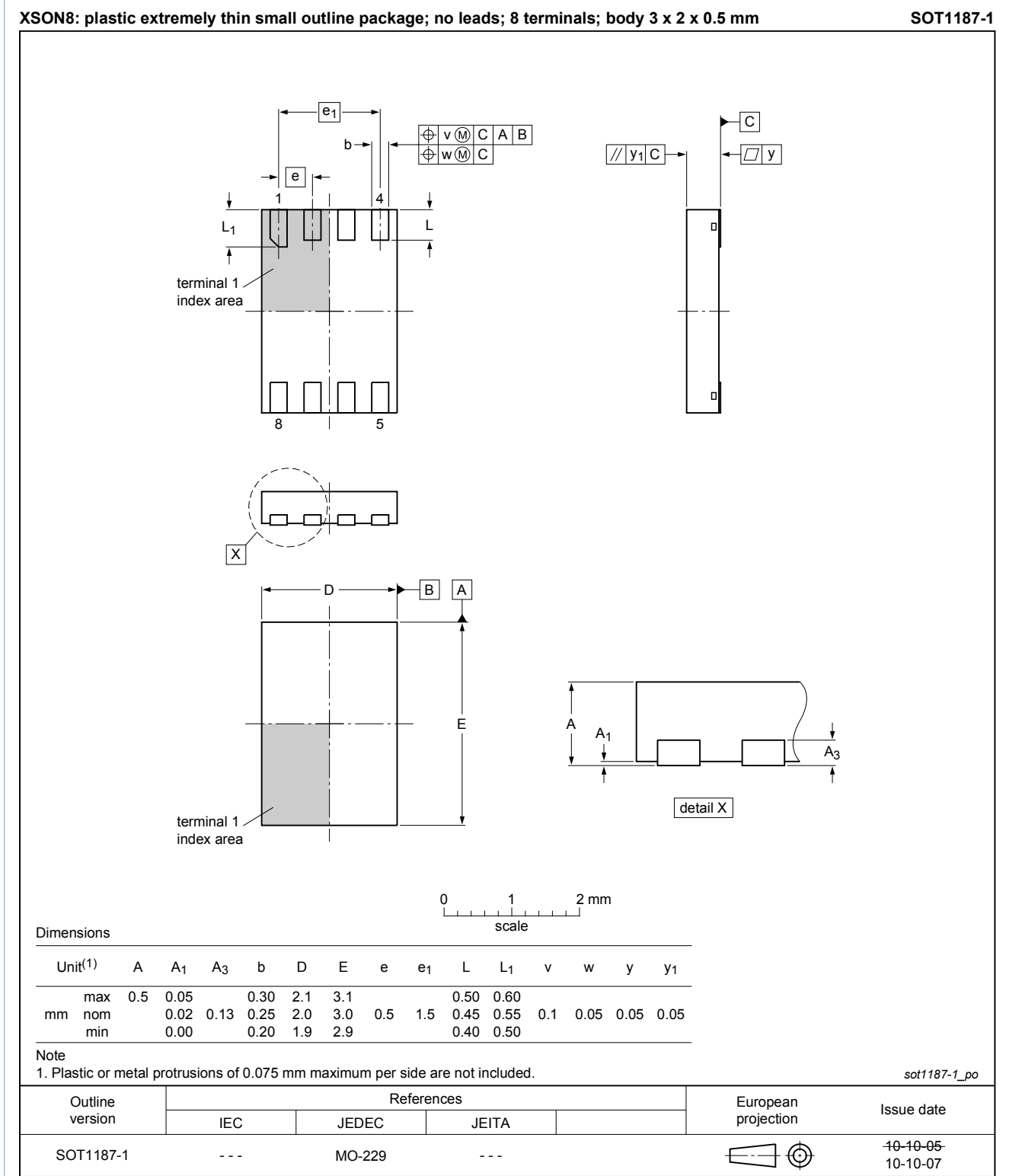


Fig. 1. Package outline XSON8 (SOT1187-1)

3. Legal information

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